

--12. (Amended) A stencil printer having a heat-sensitive stencil, said heat-sensitive stencil being provided with imagewise perforations and comprising a porous resin layer, and a resin film laminated on said porous resin layer, and a thin resin layer interposed between said porous resin layer and said resin film.

--13. (Amended) A method of preparing a heat-sensitive stencil comprising a porous resin layer, and a resin film laminated on said porous resin layer, and a thin resin layer interposed between said porous resin layer and said resin film, said thin resin layer and said porous resin layer forming a continuous unitary body, said method comprising the steps of:

applying a wet coating composition to a surface of said resin film, said wet composition containing a resin, a first solvent capable of dissolving said resin, and a second solvent substantially incapable of dissolving said resin;

applying heat to said composition at a temperature below a boiling point of said second solvent and sufficient to vaporize at least part of said first solvent; and

drying said applied composition by applying heat to said composition at a temperature sufficient to completely vaporize said first solvent and said second solvent to form said thin resin layer and said porous layer simultaneously on said surface of said film.

--14. (Amended) A method as set forth in claim 13, wherein the weight ratio of said first resin to said second resin is greater than 1:1.

--15. (Amended) A method of preparing a heat-sensitive stencil comprising a porous resin layer, and a resin film laminated on said porous resin layer, and a thin resin